

SIEMENS

Weller®

WMB 1000 Rework System

The Weller WMB 1000 is a repair system designed to facilitate the repair of printed circuit boards requiring the replacement / reflow of micro BGA and other surface mount components.

The system is versatile, operator friendly and allows repeatable solder and desolder repair processes.

The equipment comprises a power unit, programmable process timer with digital readout, swing arm with integral heating element, temperature sensor, vacuum pick up and operating instructions.

The WMB1000 is available either with underboard heating or without.

Process profiles are controlled from a programmable process timer which can store 30 programs. The process timer is lockable by a key operated switch with a removeable key.

Each program has 6 parameters, which are individually selected to suit the repair function required.

A functional design feature of the system is the swing arm. This feature provides the mounting for the slim line solder head which is protected by a transparent polycarbonate shield, to protect the operator and at the same time allow an uninterrupted view of the rework process. The swing arm can be swung to the operators left to allow clear access to the board under repair.

The rework process can only be started when the swing arm is in the central working position.

In operation air is fed through the soldering head where heating occurs and is then directed through shaped hot air nozzle onto the component under repair, according to the parameters defined by the process timer.



The soldering head has allow thermal mass which allows rapid heat up and optimum performance.

Operation

The board must be placed in position on the board holder and the swing arm brought to the central working position. The soldering head will be lowered into position so that the hot air nozzle covers the component. The height of nozzle above the component is fixed by an adjustable stop.

The start command will then initiate the assigned programme, at the end of the process an audible tone will indicate that the process is complete and the operator can then raise the solder head and push the swing arm to the left to allow access to the board.

If it is required to remove the component, then it is necessary to initiate the desolder function before the end of the reflow function, vacuum will automatically be switched on at the end of the process and the vacuum lift activated to raise the component from the board.

A number of gas nozzles is available to match a large range of micro BGA, CSP and SMD components.

With the new WMB 1000 Rework System Weller offers an optimal solution to different surface components.

*WMB 1000 Rework System
Order No.: 5 33 566 99 (without bottom heater)
5 33 546 99 (with bottom heater)*